

# Freescale Semiconductor

**Application Note** 

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# Production Flash Programming

Techniques for Production Programming the 56F8300 and 56F8100 Families of Devices, Flash Memory Blocks

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**Note:** All references to Data Flash in this document apply only to the 56F8300 family of devices; the 56F8100 devices do not support Data Flash.

# 1. Introduction

This document presents techniques and detailed information on production programming of the Program, Data, and Boot Flash memory blocks in the 56F8300 and the Program and Boot Flash memory blocks in the 56F8100 components. This is distinct from the developmental loading of the Flash blocks that is achieved using developmental tools such as the Metrowerks CodeWarrior for Freescale debugger.

There are four ways to program the Flash blocks in a factory environment:

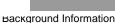
- Using the Serial Bootloader present in the Boot Flash
- Using a commercially-available device programmer
- Using the JTAG/OnCE<sup>TM</sup> port
- Using GPIO pins with a custom bootloader

The first two methods do not require any developmental effort to use. Using the JTAG/OnCE port currently requires the user to develop his own loader program. Using the GPIO pins to obtain the Flash programming data would also require the customer to develop his own loader program.

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# **Background Information**

As a starting point, all methods require an application to be created using the CodeWarrior development tools. This application must be specifically targeted to operate correctly from the internal Flash. The Freescale CodeWarrior Development tools includes information as well as code to aid in the development of the application. It is highly recommended that a developer start with the appropriate Processor Expert (PE) stationery. This will greatly facilitate the development of the application, and includes all the elements required to create embedded applications targeting internal Flash or external memory. During development and debug of the application, the CodeWarrior tool can be used to program the internal Flash and to debug the program while running from Flash. Once the development and test are complete, the CodeWarrior tool can also be used to generate the source file containing the executable image of the Program, Data and Boot Flash blocks. In this case, the source file is an S-record file. The S-record file contains the hex machine code and hex data information formatted in a text file containing a series of S3-type S-records. Refer to Appendix A at the end of this document for a detailed description of the format of the S-record file.

The CodeWarrior tool normally uses .elf files to store the application executable and to program the Flash blocks in the devices. The user must specifically configure the CodeWarrior tool to create the S-record file. Please refer to the CodeWarrior IDE Targeting DSP56800 Manual for information on how to turn on S-record generation. The CodeWarrior tool generates three separate types of S-record files:

- output\_filename.p.S contains the Program and Boot Flash image
- output filename.x.S contains the Data Flash image
- output filename. S contains the combined Program, Boot and Data Flash images

The S-record file is the source file used by all the methods of production Flash programming. The file to use when performing Flash programming will generally be the combined file, containing the Program, Boot, and Data Flash image.

## 2.1 Considerations for Choosing a Production Programming Method

A fundamental decision to be made is whether to initially program the devices after they have been soldered to the circuit board, or to initially program the devices before they are placed onto the circuit board. Programming with the Boot Flash Serial Bootloader, programming via the JTAG/OnCE port and the GPIO Flash programming mode are primarily intended as in-circuit programing methods. The bulk device load method is an out-of-circuit programming method, which allows programming the 56F8300 and 56F8100 devices in advance of the production run.

An additional consideration is which Flash blocks are to be programmed. The 56F8300 and 56F8100 products do not allow for software to run from a Flash block that is concurrently being erased and programmed. Because all 56F8300 products have multiple Program Flash blocks, this is not a significant restriction, but does require advance planning with the set-up of the Flash programming algorithms. For example, the Serial Bootloader is programmed into the Boot Flash at the factory, and allows only for the programming of the Program and Data Flash blocks because it restricts itself to only taking space in the Boot Flash. Therefore, it always runs from Boot Flash and cannot reprogram any portion of the Boot Flash block. The Serial Bootloader can be used to load all Flash blocks by implementing custom loader software that is loaded into the Program Flash, then used to program the Boot Flash. By switching back and forth, all combinations of Flash programming can be implemented. The Freescale Processor Expert for the 56F8300 and 56F8100 devices includes all software components needed to write such an application.



Since the JTAG/OnCE port and the bulk device loader mode options do not require that software be run from any of the Flash blocks, they can reprogram any block without special considerations. The 56F8300 and 56F8100 chips are fully field reprogrammable, requiring no special voltages or external hardware to perform this function. The stock Serial Bootloader fully supports field upgrades.

There is another option to consider. All of the 56F8300 and 56F8100 devices also contain on-chip program RAM. A bootloader can be loaded into this RAM and, from there, all Flash blocks can be reprogrammed.

All in-circuit Flash loading methods require that the target hardware conforms to certain minimal standards. For the Serial Bootloader, these standards require that:

- The SCI port must be accessible for serial communications
- To enable proper SCI communications, the external clock for the components must be set to the recommended frequency. 8MHz is recommended for 56F8300 amd 56F8100 components.

Although the known external clock frequencies are necessary to ensure proper SCI communications, it's possible to drive the clock inputs during Serial Bootloading, then run the normal program at a different clock frequency. In general, this will not be necessary, since in all likelihood the best choice for the external operating frequency for the target circuit board will be the same frequency required by the Serial Bootloader.

Using the JTAG/OnCE port method requires only that a subset of the JTAG/OnCE pins be made available. Please refer to Section 3.4 for details.

Using the GPIO port method would require access to any user-specified GPIO pins that the user-defined bootloader software specified.

The approximate speeds at which the Flash blocks can be programmed with the various methods are:

- SCI Serial Bootloader version 1.01 = 2495 words per second
- **CAN Serial Bootloader** version 1.01 = 3706 words per second
- **Bulk device programmer** = 800 words per second
- In-circuit JTAG/OnCE port = 800 words per second (using a parallel port command converter).

# 3. Programming Method Details

#### 3.1 Serial SCI Bootloader

The software and protocol for this loader and how to use it are fully described in the Metrowerks on-line help and web site (see **References**). Please refer to the SCI Bootloader application information in the **56F83xx SCI/CAN Bootloader User Manual** for the processor being used. This manual has detailed information on how to use the Serial Bootloader and how to prepare your application for loading using the Serial Bootloader.

Table 3-1. Details of SCI Serial Bootloader Versions 1.01

Version	Baud Rate	Flow Control	Word Format
1.01	115,200bps	Xon/Xoff	8 data bits, no parity, 1 stop bit



**Figure 3-1** shows a possible hardware configuration for using the Serial Bootloader to program the device in-circuit. This is one of many possible hardware configurations that will support the use of the Serial Bootloader to program the device.

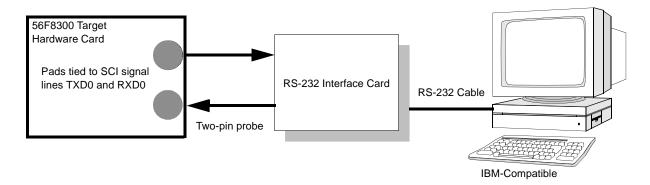


Figure 3-1. One Hardware Configuration for SCI Serial Bootloader

The configuration in **Figure 3-1** shows how the Serial Bootloader can be used, even though the target hardware has no additional connectors or RS-232 serial drivers. In addition, using an IBM-compatible computer is not required--any host capable of providing the required serial stream and the protocol can be used.

In general, it's easiest to use the Serial Bootloader program by leaving it in place in the Boot Flash without reprogramming the Boot Flash. The Serial Bootloader can be used effectively for field upgrades to the Program and Data Flash. It can also be used to replace the firmware in the Boot Flash, as shown in **Figure 3-2**.



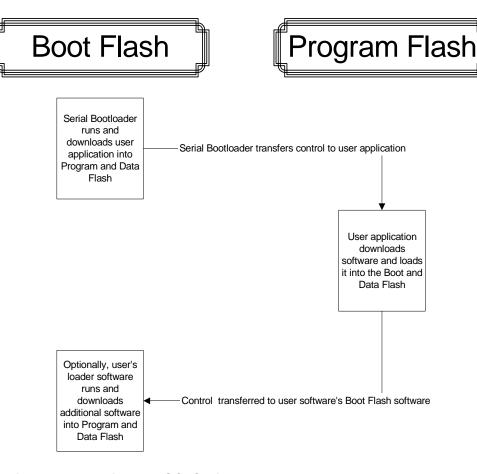


Figure 3-2. Using the SCI Serial Bootloader to Program Boot Flash

#### 3.2 Serial CAN Bootloader

The software and protocol for this loader and how to use it are fully described in the Metrowerks on-line help and web site (see **References**). Please refer to the CAN Bootloader application information in the **56F83xx SCI/CAN Bootloader User Manual** for the processor being used. This manual has detailed information on how to use the Serial Bootloader and how to prepare your application for loading using the Serial Bootloader.

The CAN Bootloader application is not present in the Boot Flash when the device is received from the factory. If the CAN Bootloader is to be used, it must first be programmed into the Boot Flash in a manner similar to that described in **Figure 3-2**.

Table 3-2. Details of CAN Serial Bootloader Versions 1.01

Version	Baud Rate
1.01	500,000bps



**Figure 3-3** shows a possible hardware configuration for using the CAN Bootloader to program the device in-circuit. This is one of many possible hardware configurations that will support the use of the CAN Bootloader to program the device.

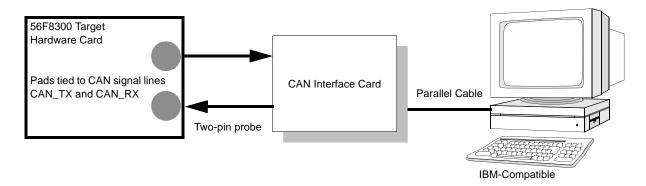


Figure 3-3. One Hardware Configuration for Serial Bootloader

#### 3.3 Bulk Device Loader

In this method, the devices are programmed out-of-circuit in a device loader. The programming can be performed using your own resources, or possibly through your distributor or another value-added reseller. The device programmer can also be used to program the Program, Data, and Boot Flash blocks. The device programmer can be used to load a complete and final application, or simply a custom Bootloader program placed into the Boot Flash area. Later, the final or complete application can be loaded using the custom Bootloader.

Please check www.bpmicro.com for device programmers from BP Microsystems support.

#### 3.4 In-circuit JTAG/OnCE Port

To use this method, the user must provide access from his host computer to the JTAG/OnCE port signals on the devices. **Table 3-3** shows the required signals. If the programming set-up uses a standard command converter to interface to the JTAG signals, then a standard JTAG pin header connector must be present on the custom card. An example of this is present on the 56F8346 EVM; information on it is also included in the **56F8346 Evaluation Module User Manual**, which can be downloaded from Freescale's website at: http://freescale.com.



Table 3-3. Required JTAG/OnCE Signals

Signal	Signal Description	Required
TDI	<b>Test Data Input</b> —This input pin provides a serial input data stream to the TAP and the TLM. It is sampled on the rising edge of TCK. TDI has an on-chip pull-up resistor which can be disabled through SIM_PUDR register in the SIM module.	Yes
TDO	Test Data Output—This tri-state output pin provides a serial output data stream from the Master TAP, or 56800E core TAP Controller. It is driven in the Shift-IR and Shift-DR controller states of the TAP Controller state machines. Output data changes on the falling edge of TCK.	Yes
TCK	Test Clock Input—This input pin provides the clock to synchronize the test logic and shift serial data to and from all TAP Controllers and the TLM. If the EOnCE module is not being accessed using the Master or 56800E core TAP Controllers, the maximum TCK frequency is 1/4 the maximum frequency for the 56800E core. When accessing the EOnCE module through the 56800E core TAP Controller, the maximum frequency for TCK is 1/8 the maximum frequency for the 56800E core. The TCK pin has a pull down non-disabled resistor.	Yes
TMS	Test Mode Select Input—This input pin is used to sequence the TAP Controller's TLM state machine. It is sampled on the rising edge of TCK. TMS has an on-chip pull-up resistor which can be disabled through SIM_PUDR register in the SIM module.	Yes
TRST	<b>Test Reset</b> —This input pin provides an asynchronous reset signal to the TLM and all TAP Controllers. If the JTAG is not going to be used, prevent signal interference by holding it low during operation.	Yes

The CodeWarrior tool can be used to download the program. A Windows application with source code to demonstrate how to program the devices over the JTAG/OnCE port is documented in the application note, "Programming On-Chip Flash Memories of DSP56F80x DSPs using the JTAG/OnCE Interface", AN1935. This application is available in the FAQs. Detailed information on how to program using the JTAG/OnCE port is available and can be requested from your Freescale sales representative.



## 3.5 GPIO Flash Programming Mode

This mode requires the customer to define his own definition of GPIO Flash programming pin definitions and code load protocol. He would then have to develop an appropriate bootload application to program into the Boot Flash. This approach would also require the customer to provide access to the required pins for his program loading.

# 4. Conclusion

The 56F8300 and 56F8100 components are very flexible in programming Flash blocks. In this application note, several methods have been presented for programming the Flash blocks in a production environment. One of these methods, or a variation of it, should meet your production Flash programming requirements.

# 5. References

The following materials were used to produce this paper:

- 1. CodeWarrior IDE Targeting 56F8300 Manual CodeWarrior for Freescale DSP56800E Embedded Systems, CWDSP56800E
- 2. Targeting Freescale 56F8300 Platform, Processor Expert
  CodeWarriorTM Development Studio for 56800/E Hybrid Controllers with Processor Expert, CW568x
- 3. 56F83xx Evaluation Module Hardware User Manual for the device being implemented
- 4. 5683xx SCI/CAN Bootloader User Manual, MC56F83xxBLUM
- 5. Programming On-Chip Flash Memories of DSP56F80x DSPs using the JTAG/OnCE Interface, AN1935
- 6. Metrowerks help:

www.metrowerks.com/MW/support or support@metrowerks.com



# Appendix A S-Record Specification

**Note:** All references to Data Flash in the appendix apply only to the 56F8300 family of devices; the 56F8100 devices do not support Data Flash.

- 1) Use only S0, S3 and S7 records
- 2) Three S-Record files are built with every compile. The first contains the contents of all initialized PROGRAM (P) Memory contents. The second file contains the contents of all initialized DATA (X) Memory contents.
- 3) The third S-Record file (the "combined" file) is roughly a concatenation of the P file with the X file (P followed by X). The S3 data records targeted for X shall have an offset of 0x02000000 added to their byte address fields. There shall be only a single pair of S0 and S7 records for the entire combined file.

#### **Notes:**

- The P (and combined) file may contain: Program Flash contents, Program RAM contents, Boot Flash contents
- The X (and combined) file may contain: Data Flash contents, Data Ram contents
- The device programming algorithm shall be address range aware
  a) The byte address fields of S3 data records are examined by the device programming algorithm to determine which Flash memory to access
  - b) The offset of 0x02000000 for X data records is required because the P and X memories within the 56F8300 devices both start at address 0. (S-Records don't normally support overlapping memories; defining an offset is the most expedient work-around for the problem.)
  - c) Data specified for RAM locations shall be ignored by the device programming algorithm.
- 4) Unique codes shall reside in the P, X and combined S0 header records. In this manner, the S0 records will identify the subsequent contents as either P, or X, or combined. The proposed S0 header records are as follows:

#### Code Example A-1. S0 Record for the P File

S0 0C 00000000 50 52 4F 47 52 41 4D DB (Hex ASCII for: P R O G R A M)

#### Code Example A-2. S0 Record for the X File

S0 09 00000000 44 41 54 41 DC (Hex ASCII for: D A T A)



#### Code Example A-3. S0 Record for the Combined File

SO 11 00000000 50 52 4F 47 52 41 4D 26 44 41 54 41 96

(Hex ASCII for: P R O G R A M & D A T A)

#### **Notes:**

The device programming algorithm will not be expected to recognize contents within any S0 record. The S0 content is only to aid with human recognition of file contents and to assist in content recognition by future tools.

5) S3 data shall not split across a processor word size (16 bits). In other words, there shall be an even number of "data" bytes within each S3 record.

Sample S-Record files for the 56F8300 and 56F8100 follow. (Spaces have been inserted for improved readability in this document; "CS" is a space holder for the checksum byte.) The address fields of the S3 record shall be conventional BYTE addresses and byte data shall be represented in the Little-endian format. (The Least Significant Byte [LSB] is located at the lowest address.)

#### Notes:

- In this manner, the constituent P or X S-Record files can be used to program any conventional (external) non-volatile memory devices, without the need for any additional S-Record manipulation utility programs
- 56F8300 and 56F8100 processors have a native 16 bit word. Likewise, the Flash memories are programmed with 16-bit words and all addresses are interpreted as word addresses
- To get from the S-Record Byte address to the 56F8300 and 56F8100 16-bit Word address, divide the S-Record address field value by 2. For X memory, first subtract the 0x02000000 offset, then unscramble the little-endian format to recognize the data words.

#### Code Example A-4. Sample P File

S0	0C	00000000	50	52	4F	47	52	41	4D	DB		"PROGRAM"
S3	0D	00000000	10	32	11	32	12	32	13	32	CS	
S3	0D	80000008	14	32	15	32	16	32	17	32	CS	
S3	0D	00000010	18	32	19	32	1A	32	1в	32	CS	
S3	0D	00040000	10	В2	11	В2	12	В2	13	В2	CS	Boot Flash starts at word
S3	0D	00040008	14	В2	15	В2	16	В2	17	В2	CS	address 20000
s7	05	00000000	CS									(byte address 40000)

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## Code Example A-5. Sample X File

S0	09	00000000	44	41	54	41	DC					"DATA"
S3	0D	00002000	10	A2	11	A2	12	A2	13	A2	CS	<b>Note:</b> There is no offset
S3	0D	00002008	14	A2	15	A2	16	A2	17	A2	CS	used in the stand-alone
s7	05	0000000	CS									X S-Record file.
												In this example, word
												address 1000 is the first
												location to be programmed.

# Code Example A-6. Sample Combined File

S0	11	00000000	50	52	4F	47	52	41	4D	26	44	41	54	41	96	"PROGRAM	
S3	0D	0000000	10	32	11	32	12	32	13	32	CS					& DATA"	
S3	0D	80000008	14	32	15	32	16	32	17	32	CS						
S3	0D	00000010	18	32	19	32	1A	32	1в	32	CS						
S3	0D	00040000	10	В2	11	В2	12	В2	13	В2	CS			Во	ot Fla	sh starts at word	
S3	0D	00040008	14	В2	15	В2	16	В2	17	В2	CS			ad	dress 2	20000	
S3	0D	02002000	10	A2	11	A2	12	A2	13	A2	CS			Bi	g offse	et of 0x02000000	
S3	0D	02002008	14	A2	15	A2	16	A2	17	A2	CS			sig	nifies	X data follows	
s7	05	00000000	CS														

# **S-Record Explanation**

SO O5	00000000	(data)	CC
50.05	00000000	uata	$\mathcal{L}_{\mathcal{O}}$

\$0 \$3 \$7	S0 is a header record S3 is data S7 terminator for block of S3
05	(hex) 5 bytes follow
00000000	32 bits of byte addresses
CS	The Least Significant Byte (LSB) of the one's complement of the sum of the values represented in the pairs of characters making up the record length, address, and the data fields



After programming the 56F8300 or 56F8100 with either the combined file or both stand-alone P and X files, a debugger dump would yield results like those in the following Code Examples:

#### Code Example A-7. Dump of Program (P) Flash

```
address p:00 0000 = 3210
address p:00 0001 = 3211
address p:00 0002 = 3212
address p:00 0003 = 3213
address p:00 0004 = 3214...
```

#### Code Example A-8. Dump of Boot Flash

```
address p:02 0000 = B210

address p:02 0001 = B211

address p:02 0002 = B212

address p:02 0003 = B213...
```

## Code Example A-9. Dump of Data (X) Flash

```
address x:00 1000 = A210
address x:00 1001 = A211
address x:00 1002 = A212
address x:00 1003 = A213
address x:00 1004 = A214...
```

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References





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